

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC0923NDI	**Issued**	08. February 2022
MA#	MA005698612		
Package	PG-TISON-8-2	**Weight***	96.33 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.210	0.22	0.22	2184	2184
chip_2	inorganic material	silicon	7440-21-3	0.210	0.22	0.22	2184	2184
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		107	
	non noble metal	zinc	7440-66-6	0.041	0.04		426	
	non noble metal	iron	7439-89-6	0.822	0.85		8529	
	non noble metal	copper	7440-50-8	33.360	34.63	35.53	346309	355371
wire	noble metal	gold	7440-57-5	0.062	0.06	0.06	642	642
encapsulation	organic material	carbon black	1333-86-4	0.096	0.10		996	
	plastics	epoxy resin	-	4.941	5.13		51292	
	inorganic material	silicondioxide	60676-86-0	42.934	44.58	49.81	445692	497980
leadfinish	non noble metal	tin	7440-31-5	1.108	1.15	1.15	11502	11502
plating	noble metal	silver	7440-22-4	0.186	0.19	0.19	1929	1929
solder	non noble metal	tin	7440-31-5	0.015	0.02		154	
	noble metal	silver	7440-22-4	0.019	0.02		193	
	non noble metal	lead	7439-92-1	0.709	0.74	0.78	7363	7710
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			36	
	non noble metal	zinc	7440-66-6	0.014	0.01		145	
	non noble metal	iron	7439-89-6	0.279	0.29		2892	
	non noble metal	copper	7440-50-8	11.312	11.74	12.04	117425	120498
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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